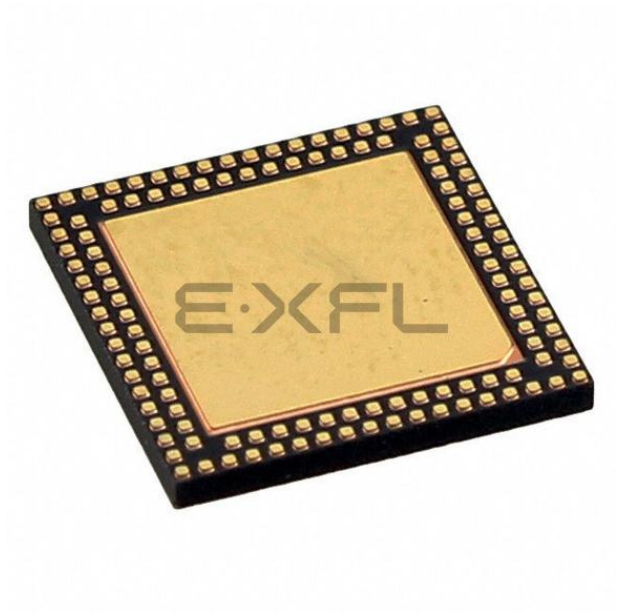

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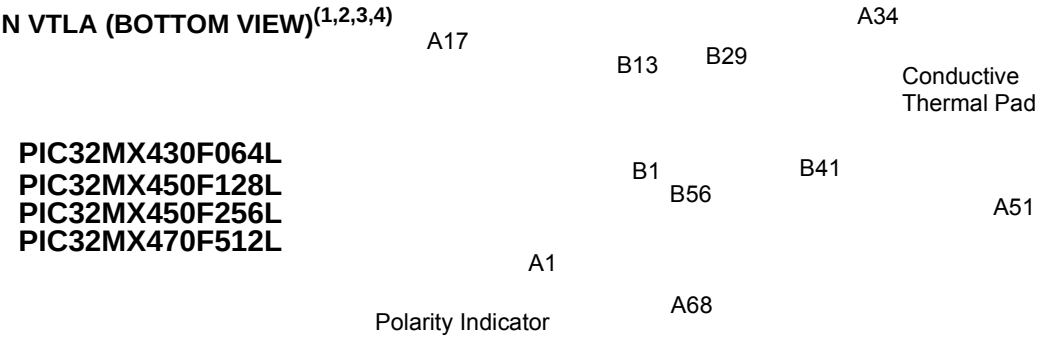
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	124-VFTLA Dual Rows, Exposed Pad
Supplier Device Package	124-VTLA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx370f512lt-v-tl

TABLE 7: PIN NAMES FOR 124-PIN DEVICES (CONTINUED)

124-PIN VTLA (BOTTOM VIEW)(1,2,3,4)



Package Bump #	Full Pin Name	Package Bump #	Full Pin Name
B7	$\overline{MCLR}$	B32	SDA2/RA3
B8	VSS	B33	TDO/RA5
B9	TMS/CTED1/RA0	B34	OSC1/CLKI/RC12
B10	RPE9/RE9	B35	No Connect
B11	AN4/C1INB/RB4	B36	SCL1/RPA14/RA14
B12	VSS	B37	RPD8/RTCC/RD8
B13	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	B38	RPD10/SCK1/PMCS2/RD10
B14	PGED1/AN0/RPB0/RB0	B39	RPD0/INT0/RD0
B15	No Connect	B40	SOSCO/RPC14/T1CK/RC14
B16	PGED2/AN7/RPB7/CTED3/RB7	B41	VSS
B17	VREF+/CVREF+/PMA6/RA10	B42	AN25/RPD2/RD2
B18	AVSS	B43	RPD12/PMD12/RD12
B19	AN9/RPB9/CTED4/RB9	B44	RPD4/PMWR/RD4
B20	AN11/PMA12/RB11	B45	PMD14/RD6
B21	VDD	B46	No Connect
B22	RPF13/RF13	B47	No Connect
B23	AN12/PMA11/RB12	B48	VCAP
B24	AN14/RPB14/CTED5/PMA1/RB14	B49	RPF0/PMD11/RF0
B25	VSS	B50	RPG1/PMD9/RG1
B26	RPD14/RD14	B51	TRCLK/RA6
B27	RPF4/PMA9/RF4	B52	PMD0/RE0
B28	No Connect	B53	VDD
B29	RPF8/RF8	B54	TRD2/RG14
B30	VUSB3V3	B55	TRD0/RG13
B31	D+	B56	RPE3/CTPLS/PMD3/RE3

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: Shaded package bumps are 5V tolerant.

4: It is recommended that the user connect the printed circuit board (PCB) ground to the conductive thermal pad on the bottom of the package. And to not run non-Vss PCB traces under the conductive thermal pad on the same side of the PCB layout.

TABLE 4-1: SFR MEMORY MAP

Peripheral	Virtual Address	
	Base	Offset Start
Watchdog Timer	0xBF80	0x0000
RTCC		0x0200
Timer1-5		0x0600
Input Capture 1-5		0x2000
Output Compare 1-5		0x3000
I2C1 and I2C2		0x5000
SPI1 and SPI2		0x5800
UART1 and UART2		0x6000
PMP		0x7000
ADC		0x9000
CVREF		0x9800
Comparator		0xA000
CTMU		0xA200
Oscillator		0xF000
Device and Revision ID		0xF200
Flash Controller		0xF400
Reset		0xF600
PPS		0xFA04
Interrupts	0xBF88	0x1000
Bus Matrix		0x2000
DMA		0x3000
Prefetch		0x4000
USB		0x5040
PORTA-PORTG		0x6000
Configuration	0xBFC0	0x2FF0

REGISTER 11-8: U1EIR: USB ERROR INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS
	BTSEF	BMXEF	DMAEF(1)	BTOEF(2)	DFN8EF	CRC16EF	CRC5EF(4) / EOFEF(3,5)	PIDEF

Legend:	WC = Write '1' to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **BTSEF:** Bit Stuff Error Flag bit
- 1 = Packet is rejected due to bit stuff error
- 0 = Packet is accepted

bit 6 **BMXEF:** Bus Matrix Error Flag bit
- 1 = The base address, of the BDT, or the address of an individual buffer pointed to by a BDT entry, is invalid.
- 0 = No address error

bit 5 **DMAEF:** DMA Error Flag bit(1)
- 1 = USB DMA error condition detected
- 0 = No DMA error

bit 4 **BTOEF:** Bus Turnaround Time-Out Error Flag bit(2)
- 1 = Bus turnaround time-out has occurred
- 0 = No bus turnaround time-out

bit 3 **DFN8EF:** Data Field Size Error Flag bit
- 1 = Data field received is not an integral number of bytes
- 0 = Data field received is an integral number of bytes

bit 2 **CRC16EF:** CRC16 Failure Flag bit
- 1 = Data packet rejected due to CRC16 error
- 0 = Data packet accepted

Note 1: This type of error occurs when the module's request for the DMA bus is not granted in time to service the module's demand for memory, resulting in an overflow or underflow condition, and/or the allocated buffer size is not sufficient to store the received data packet causing it to be truncated.

2: This type of error occurs when more than 16-bit-times of Idle from the previous End-of-Packet (EOP) has elapsed.

3: This type of error occurs when the module is transmitting or receiving data and the SOF counter has reached zero.

4: Device mode.

5: Host mode.

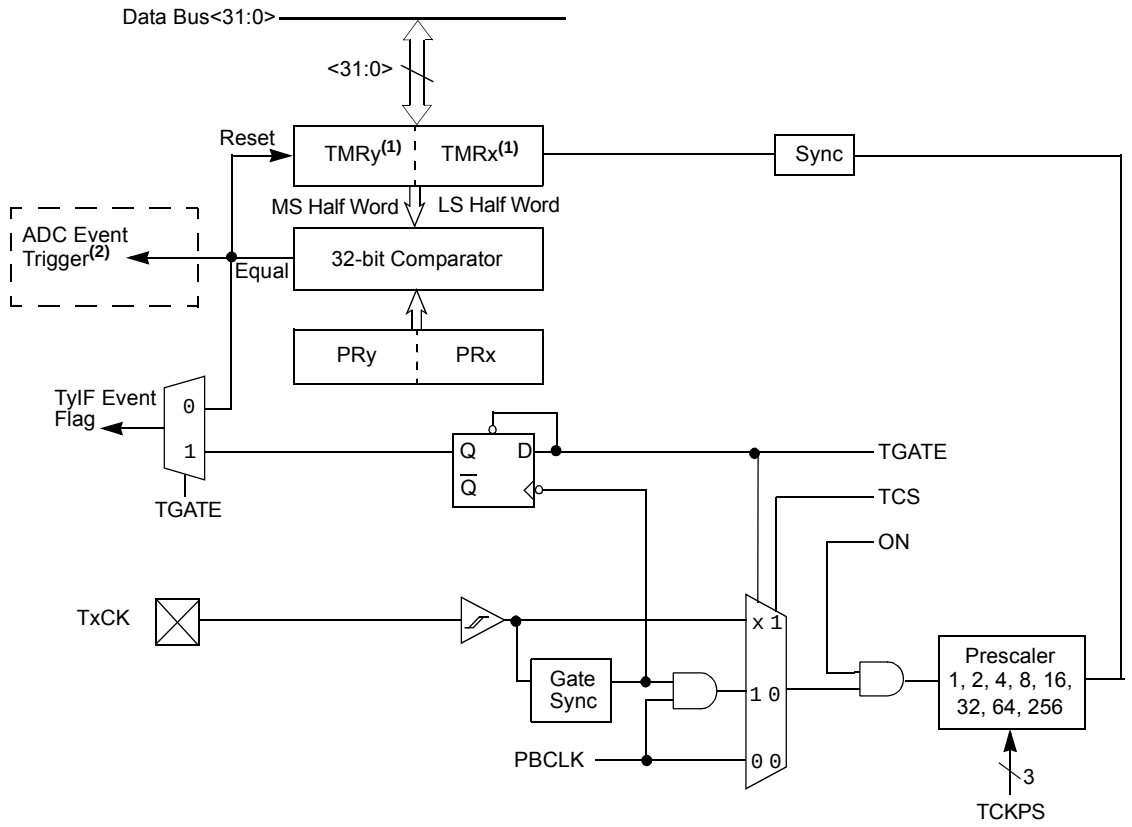
TABLE 12-10: PORTE REGISTER MAP FOR PIC32MX330F064H, PIC32MX350F128H, PIC32MX350F256H, PIC32MX370F512H, PIC32MX430F064H, PIC32MX450F128H, PIC32MX450F256H, AND PIC32MX470F512H DEVICES ONLY

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6400	ANSELE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	ANSELE7	ANSELE6	ANSELE5	ANSELE4	—	ANSELE2	—	—	00F4
6410	TRISE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	TRISE7	TRISE6	TRISE5	TRISE4	TRISE3	TRISE2	TRISE1	TRISE0	xxxx
6420	PORTE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	RE7	RE6	RE5	RE4	RE3	RE2	RE1	RE0	xxxx
6440	LATE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	LATE7	LATE6	LATE5	LATE4	LATE3	LATE2	LATE1	LATE0	xxxx
6440	ODCE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	ODCE7	ODCE6	ODCE5	ODCE4	ODCE3	ODCE2	ODCE1	ODCE0	xxxx
6450	CNPUE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CNPUE7	CNPUE6	CNPUE5	CNPUE4	CNPDE3	CNPUE2	CNPUE1	CNPUE0	xxxx
6460	CNPDE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CNPDE7	CNPDE6	CNPDE5	CNPDE4	CNPDE3	CNPDE2	CNPDE1	CNPDE0	xxxx
6470	CNCONE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6480	CNENE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CNIEE7	CNIEE6	CNIEE5	CNIEE4	CNIEE3	CNIEE2	CNIEE1	CNIEE0	xxxx
6490	CNSTATE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CN STATE7	CN STATE6	CN STATE5	CN STATE4	CN STATE3	CN STATE2	CN STATE1	CN STATE0	xxxx

Legend: x = Unknown value on Reset; — = Unimplemented, read as '0'; Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

FIGURE 14-2: TIMER2/3, 4/5 BLOCK DIAGRAM (32-BIT)(1)



Note 1: In this diagram, the use of 'x' in registers, TxCON, TMRx, PRx and TxCK, refers to either Timer2 or Timer4; the use of 'y' in registers, TyCON, TMRy, PRy, TyIF, refers to either Timer3 or Timer5.

2: ADC event trigger is available only on the Timer2/3 pair.

REGISTER 14-1: TxCON: TYPE B TIMER CONTROL REGISTER (CONTINUED)

bit 3 **T32:** 32-Bit Timer Mode Select bit(2)
1 = Odd numbered and even numbered timers form a 32-bit timer
0 = Odd numbered and even numbered timers form a separate 16-bit timer

bit 2 **Unimplemented:** Read as '0'

bit 1 **TCS:** Timer Clock Source Select bit(3)
1 = External clock from TxCK pin
0 = Internal peripheral clock

bit 0 **Unimplemented:** Read as '0'

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit is available only on even numbered timers (Timer2 and Timer4).

3: While operating in 32-bit mode, this bit has no effect for odd numbered timers (Timer3 and Timer5). All timer functions are set through the even numbered timers.

4: While operating in 32-bit mode, this bit must be cleared on odd numbered timers to enable the 32-bit timer in Idle mode.

REGISTER 18-1: SPIxCON: SPI CONTROL REGISTER (CONTINUED)

bit 4 **DISSDI:** Disable SDI bit
1 = SDI pin is not used by the SPI module (pin is controlled by PORT function)
0 = SDI pin is controlled by the SPI module

bit 3-2 **STXISEL<1:0>:** SPI Transmit Buffer Empty Interrupt Mode bits
11 = Interrupt is generated when the buffer is not full (has one or more empty elements)
10 = Interrupt is generated when the buffer is empty by one-half or more
01 = Interrupt is generated when the buffer is completely empty
00 = Interrupt is generated when the last transfer is shifted out of SPISR and transmit operations are complete

bit 1-0 **SRXISEL<1:0>:** SPI Receive Buffer Full Interrupt Mode bits
11 = Interrupt is generated when the buffer is full
10 = Interrupt is generated when the buffer is full by one-half or more
01 = Interrupt is generated when the buffer is not empty
00 = Interrupt is generated when the last word in the receive buffer is read (i.e., buffer is empty)

Note 1: When using the 1:1 PBCLK divisor, the user software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit can only be written when the ON bit = 0.

3: This bit is not used in the Framed SPI mode. The user should program this bit to '0' for the Framed SPI mode (FRMEN = 1).

4: When AUDEN = 1, the SPI module functions as if the CKP bit is equal to '1', regardless of the actual value of CKP.

19.0 INTER-INTEGRATED CIRCUIT (I^2C)

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 24. "Inter-Integrated Circuit (I^2C)"** (DS60001116), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The I^2C module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard. Figure 19-1 illustrates the I^2C module block diagram.

Each I^2C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^2C module offers the following key features:

- I^2C interface supporting both master and slave operation
- I^2C Slave mode supports 7-bit and 10-bit addressing
- I^2C Master mode supports 7-bit and 10-bit addressing
- I^2C port allows bidirectional transfers between master and slaves
- Serial clock synchronization for the I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I^2C supports multi-master operation; detects bus collision and arbitrates accordingly
- Provides support for address bit masking

20.1 Control Registers

TABLE 20-1: UART1 THROUGH UART5 REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6000	U1MODE(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6010	U1STA(1)	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	FFFF
6020	U1TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	TX8	Transmit Register								0000
6030	U1RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	RX8	Receive Register								0000
6040	U1BRG(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	Baud Rate Generator Prescaler																0000
6200	U2MODE(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6210	U2STA(1)	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	FFFF
6220	U2TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	TX8	Transmit Register								0000
6230	U2RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	RX8	Receive Register								0000
6240	U2BRG(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	Baud Rate Generator Prescaler																0000
6400	U3MODE(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6410	U3STA(1)	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	FFFF
6420	U3TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	TX8	Transmit Register								0000
6430	U3RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	RX8	Receive Register								0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 21-2: PMMODE: PARALLEL PORT MODE REGISTER (CONTINUED)

bit 5-2 **WAITM<3:0>:** Data Read/Write Strobe Wait States bits(1)

1111 = Wait of 16 TPB
•
•
•
0001 = Wait of 2 TPB
0000 = Wait of 1 TPB (default)

bit 1-0 **WAITE<1:0>:** Data Hold After Read/Write Strobe Wait States bits(1)

11 = Wait of 4 TPB
10 = Wait of 3 TPB
01 = Wait of 2 TPB
00 = Wait of 1 TPB (default)

For Read operations:
11 = Wait of 3 TPB
10 = Wait of 2 TPB
01 = Wait of 1 TPB
00 = Wait of 0 TPB (default)

Note 1: Whenever WAITM<3:0> = 0000, WAITB and WAITE bits are ignored and forced to 1 TPB cycle for a write operation; WAITB = 1 TPB cycle, WAITE = 0 TPB cycles for a read operation.

2: Address bits, A15 and A14, are not subject to automatic increment/decrement if configured as Chip Select CS2 and CS1.

3: These pins are active when MODE16 = 1 (16-bit mode).

22.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

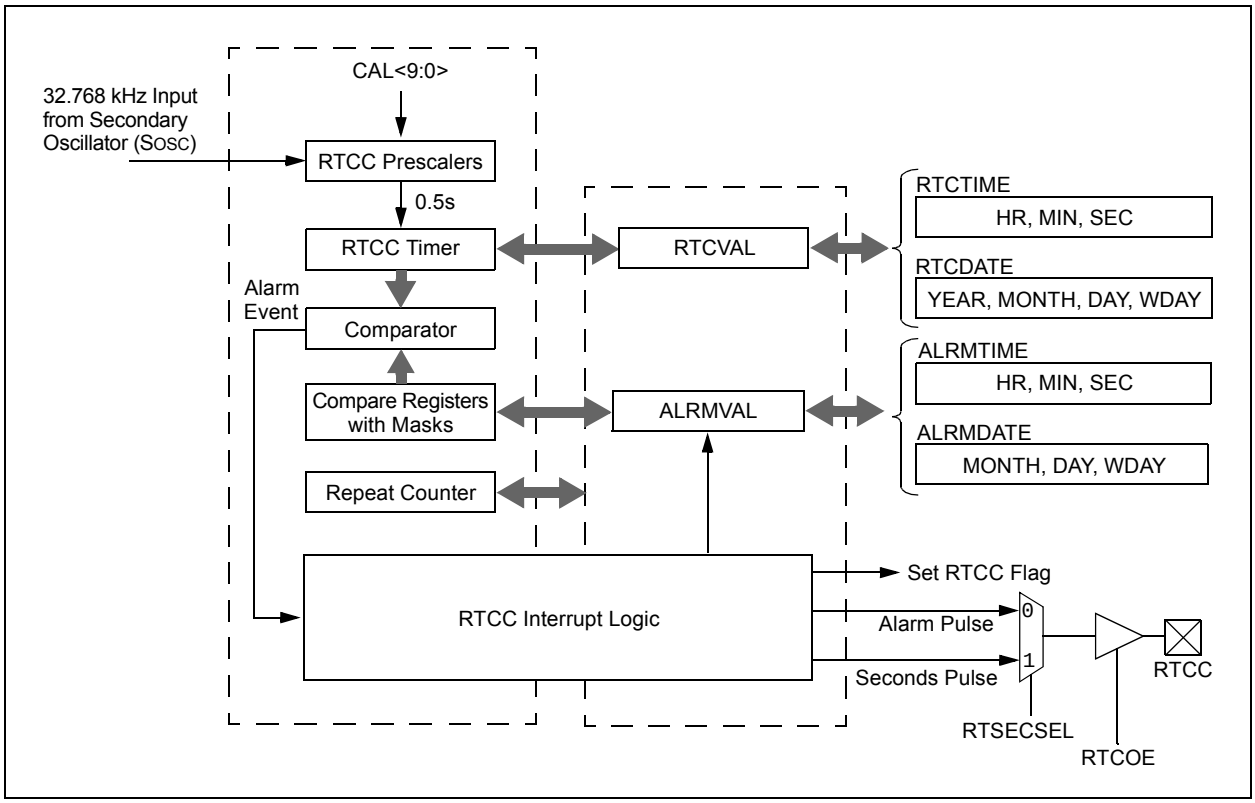
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS60001125), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

The following are key features of this module:

- Time: hours, minutes and seconds
- 24-hour format (military time)
- Visibility of one-half second period
- Provides calendar: Weekday, date, month and year
- Alarm intervals are configurable for half of a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week, one month and one year
- Alarm repeat with decrementing counter
- Alarm with indefinite repeat: Chime
- Year range: 2000 to 2099
- Leap year correction
- BCD format for smaller firmware overhead
- Optimized for long-term battery operation
- Fractional second synchronization
- User calibration of the clock crystal frequency with auto-adjust
- Calibration range: ±0.66 seconds error per month
- Calibrates up to 260 ppm of crystal error
- Requirements: External 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

FIGURE 22-1: RTCC BLOCK DIAGRAM



REGISTER 24-1: CMxCON: COMPARATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	R-0
	ON(1)	COE	CPOL(2)	—	—	—	—	COUT
7:0	R/W-1	R/W-1	U-0	R/W-0	U-0	U-0	R/W-1	R/W-1
	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Comparator ON bit(1)
- 1 = Module is enabled. Setting this bit does not affect the other bits in this register
- 0 = Module is disabled and does not consume current. Clearing this bit does not affect the other bits in this register

bit 14 **COE:** Comparator Output Enable bit
- 1 = Comparator output is driven on the output CxOUT pin
- 0 = Comparator output is not driven on the output CxOUT pin

bit 13 **CPOL:** Comparator Output Inversion bit(2)
- 1 = Output is inverted
- 0 = Output is not inverted

bit 12-9 **Unimplemented:** Read as '0'

bit 8 **COUT:** Comparator Output bit
- 1 = Output of the Comparator is a '1'
- 0 = Output of the Comparator is a '0'

bit 7-6 **EVPOL<1:0>:** Interrupt Event Polarity Select bits
- 11 = Comparator interrupt is generated on a low-to-high or high-to-low transition of the comparator output
- 10 = Comparator interrupt is generated on a high-to-low transition of the comparator output
- 01 = Comparator interrupt is generated on a low-to-high transition of the comparator output
- 00 = Comparator interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator Positive Input Configure bit
- 1 = Comparator non-inverting input is connected to the internal CV_{REF}
- 0 = Comparator non-inverting input is connected to the CxINA pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator Negative Input Select bits for Comparator
- 11 = Comparator inverting input is connected to the IV_{REF}
- 10 = Comparator inverting input is connected to the CxIND pin
- 01 = Comparator inverting input is connected to the CxINC pin
- 00 = Comparator inverting input is connected to the CxINB pin

Note 1: When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: Setting this bit will invert the signal to the comparator interrupt generator as well. This will result in an interrupt being generated on the opposite edge from the one selected by EVPOL<1:0>.

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control edge source
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 23 **EDG2MOD:** Edge 2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge 2 programmed for a positive edge response
0 = Edge 2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = Reserved
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit**(1)**
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 31-42) in **Section 31.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

31.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX330/350/370/430/450/470 AC characteristics and timing parameters.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

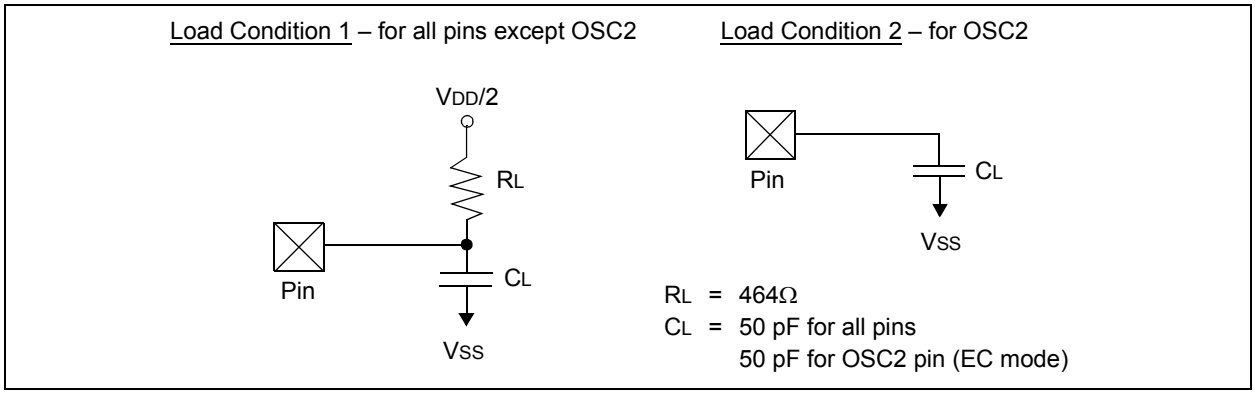


TABLE 31-17: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
DO50	COSCO	OSC2 pin	—	—	15	pF	In XT and HS modes when an external crystal is used to drive OSC1
DO56	CIO	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C mode

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 31-2: EXTERNAL CLOCK TIMING

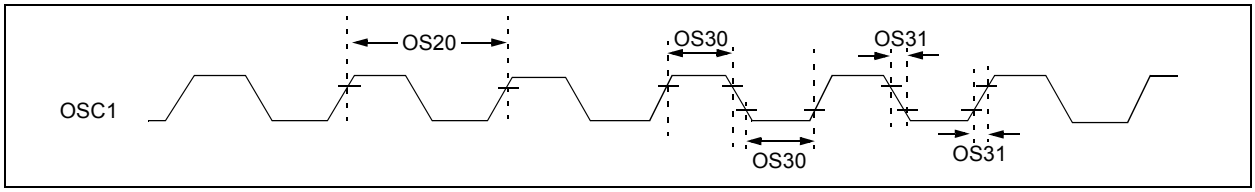
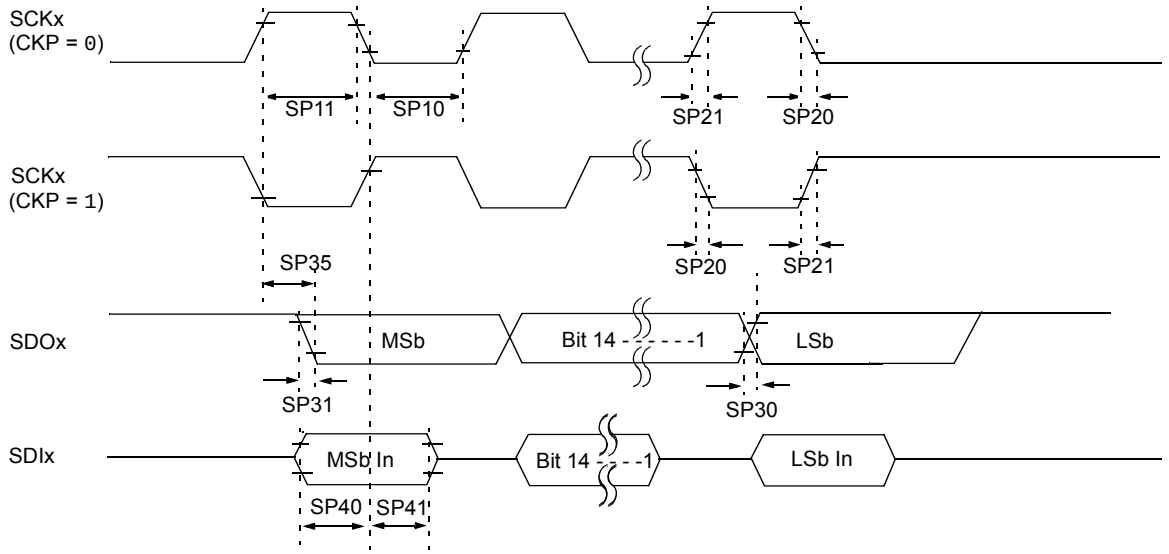


FIGURE 31-10: SPIx MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-29: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP11	TscH	SCKx Output High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 31-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

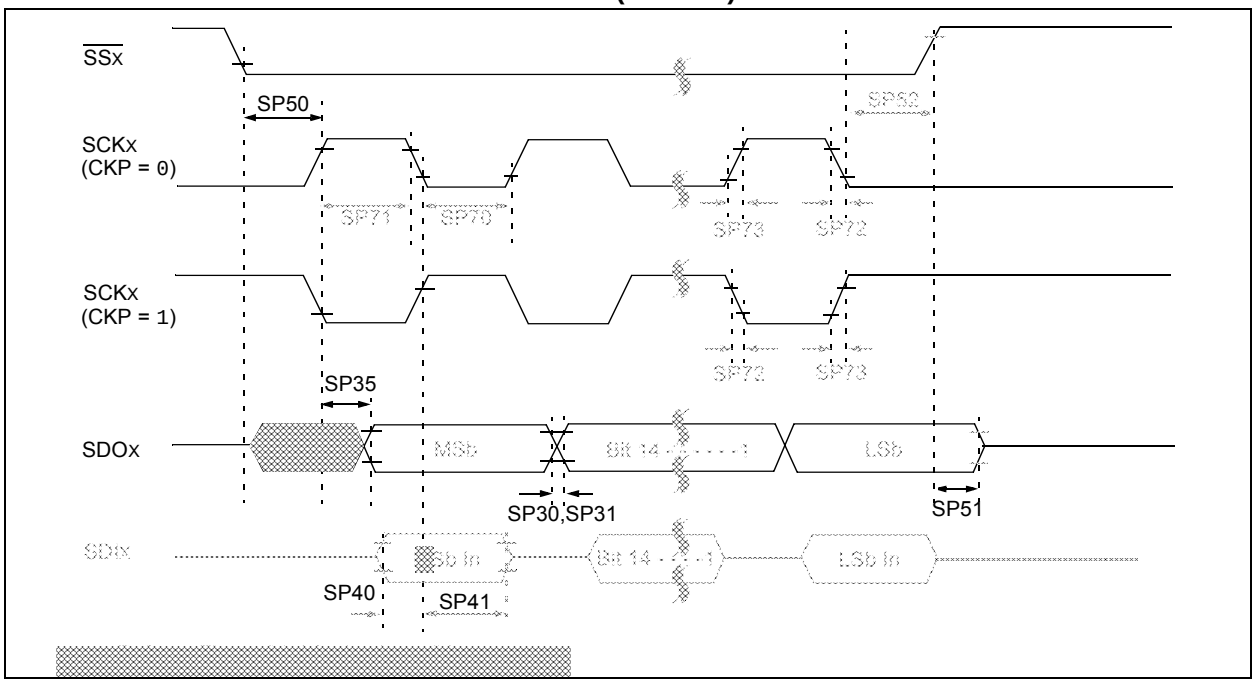


TABLE 31-31: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance **(Note 3)**	5	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 31-22: PARALLEL MASTER PORT WRITE TIMING DIAGRAM

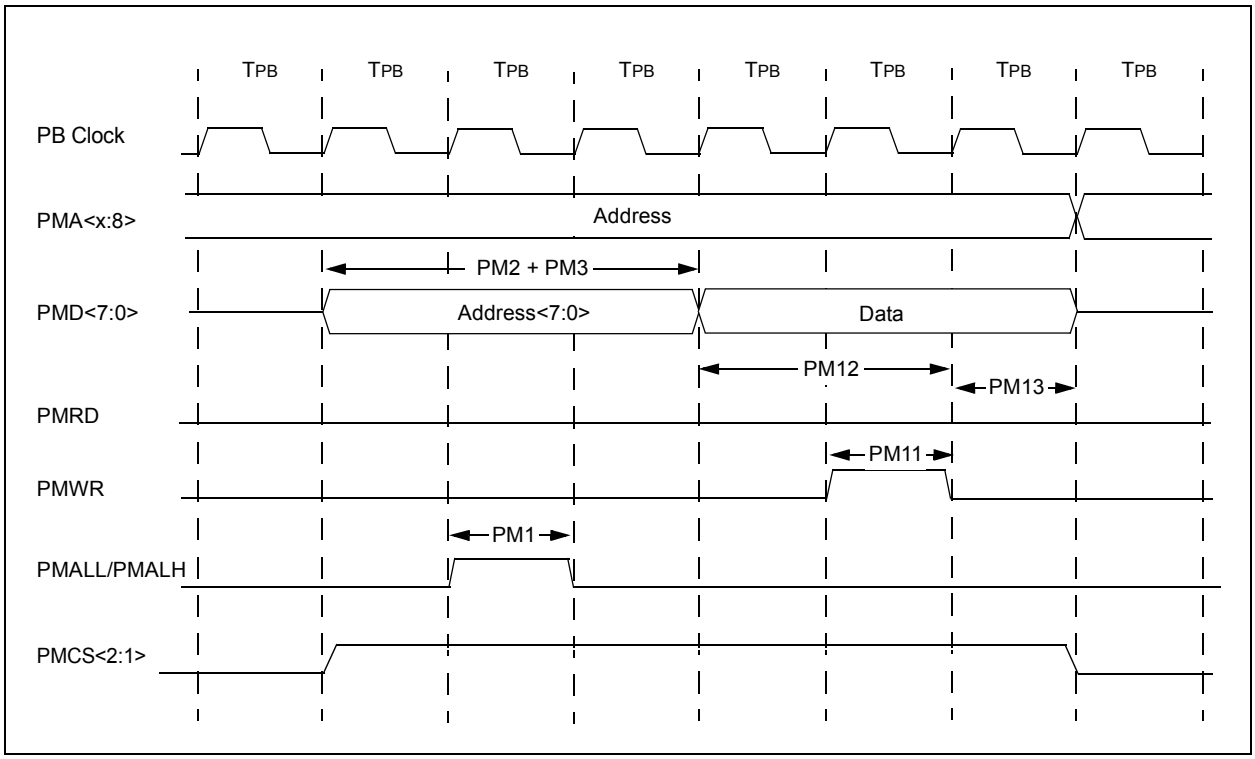


TABLE 31-40: PARALLEL MASTER PORT WRITE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
PM11	TWR	PMWR Pulse Width	—	1 TPB	—	—	—
PM12	TDVSU	Data Out Valid before PMWR or PMENB goes Inactive (data setup time)	—	2 TPB	—	—	—
PM13	TDVHOLD	PMWR or PMEMB Invalid to Data Out Invalid (data hold time)	—	1 TPB	—	—	—

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 32-9: TYPICAL IIDLE CURRENT @ VDD = 3.3V

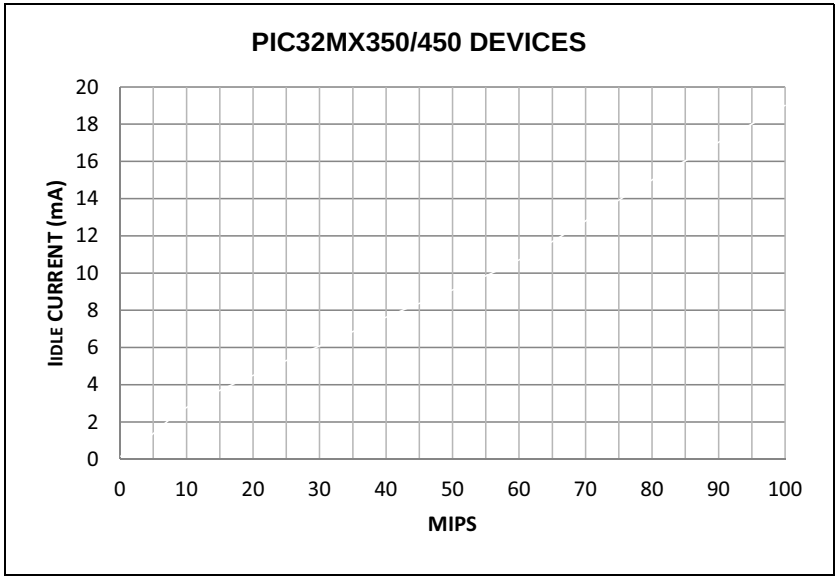


FIGURE 32-10: TYPICAL IIDLE CURRENT @ VDD = 3.3V

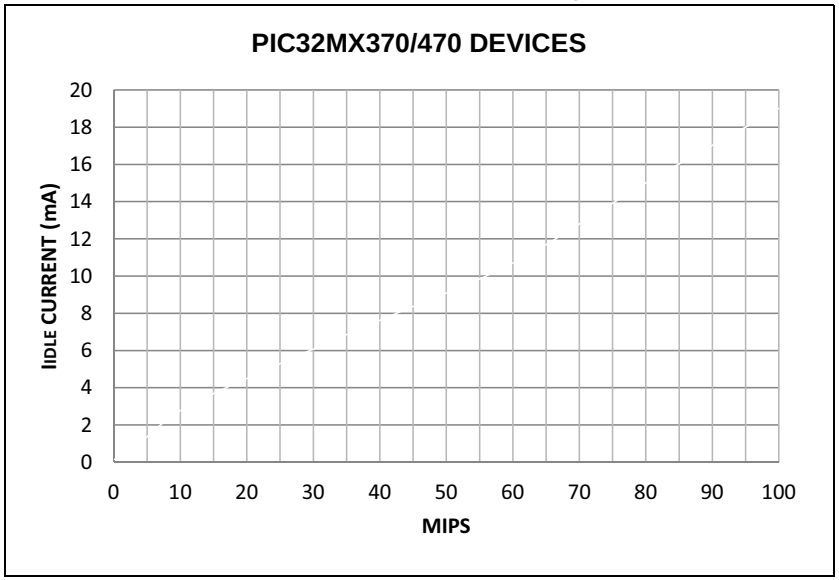


FIGURE 32-11: TYPICAL IDD CURRENT @ VDD = 3.3V

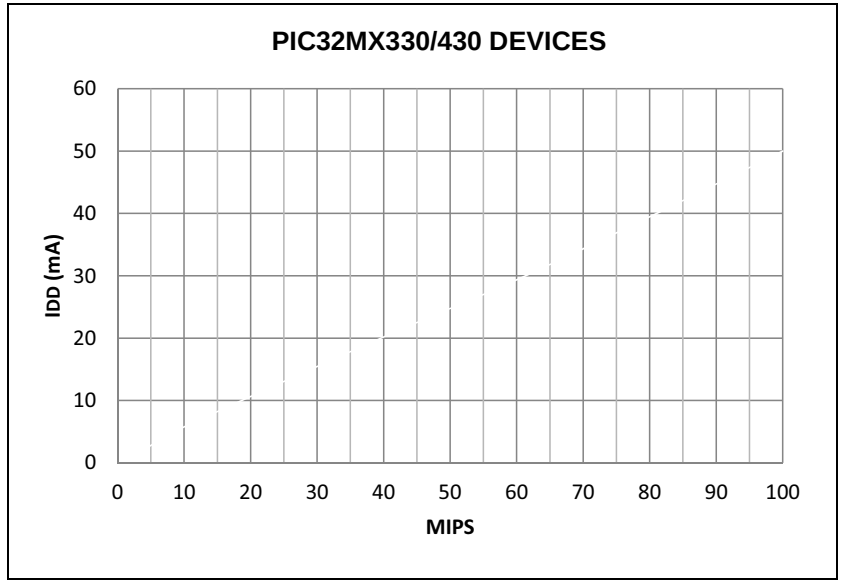
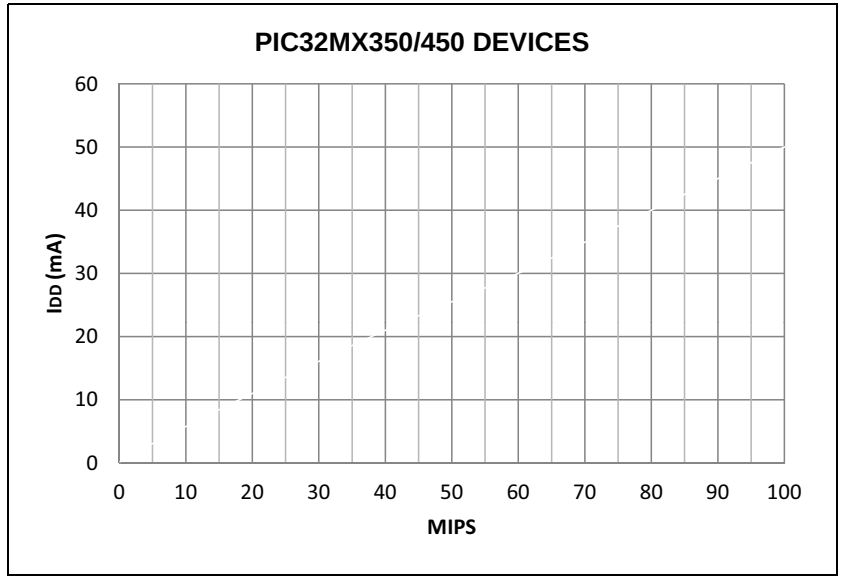
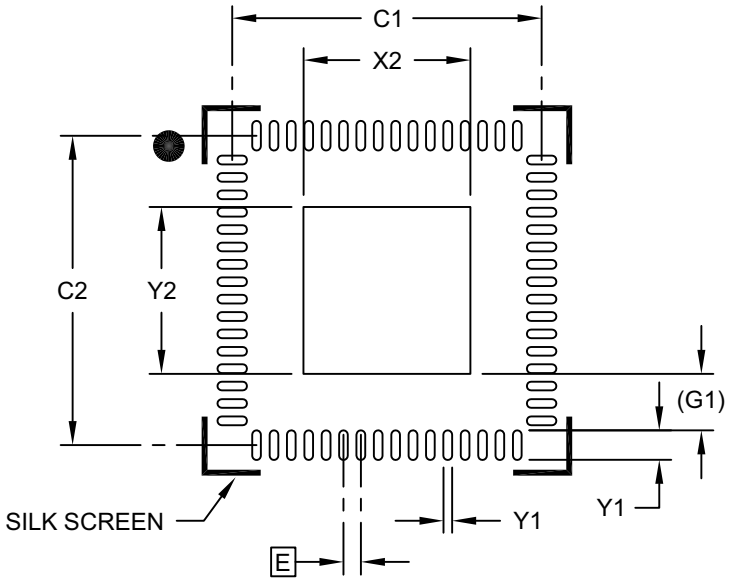


FIGURE 32-12: TYPICAL IDD CURRENT @ VDD = 3.3V



64-Lead Very Thin Plastic Quad Flat, No Lead Package (RG) - 9x9x1.0 mm Body [QFN] 4.7x4.7 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			4.80
Optional Center Pad Length	Y2			4.80
Contact Pad Spacing	C1		8.90	
Contact Pad Spacing	C2		8.90	
Contact Pad Width (X64)	X1			0.25
Contact Pad Length (X64)	Y1			0.85
Contact Pad to Center Pad (X64)	G1	1.625 REF		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2260A